



SOT1172-2

plastic thermal enhanced thin shrink small outline package;
28 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP28
Package type industry code	HTSSOP28
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-153
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	13-7-2010

Table 1. Package summary

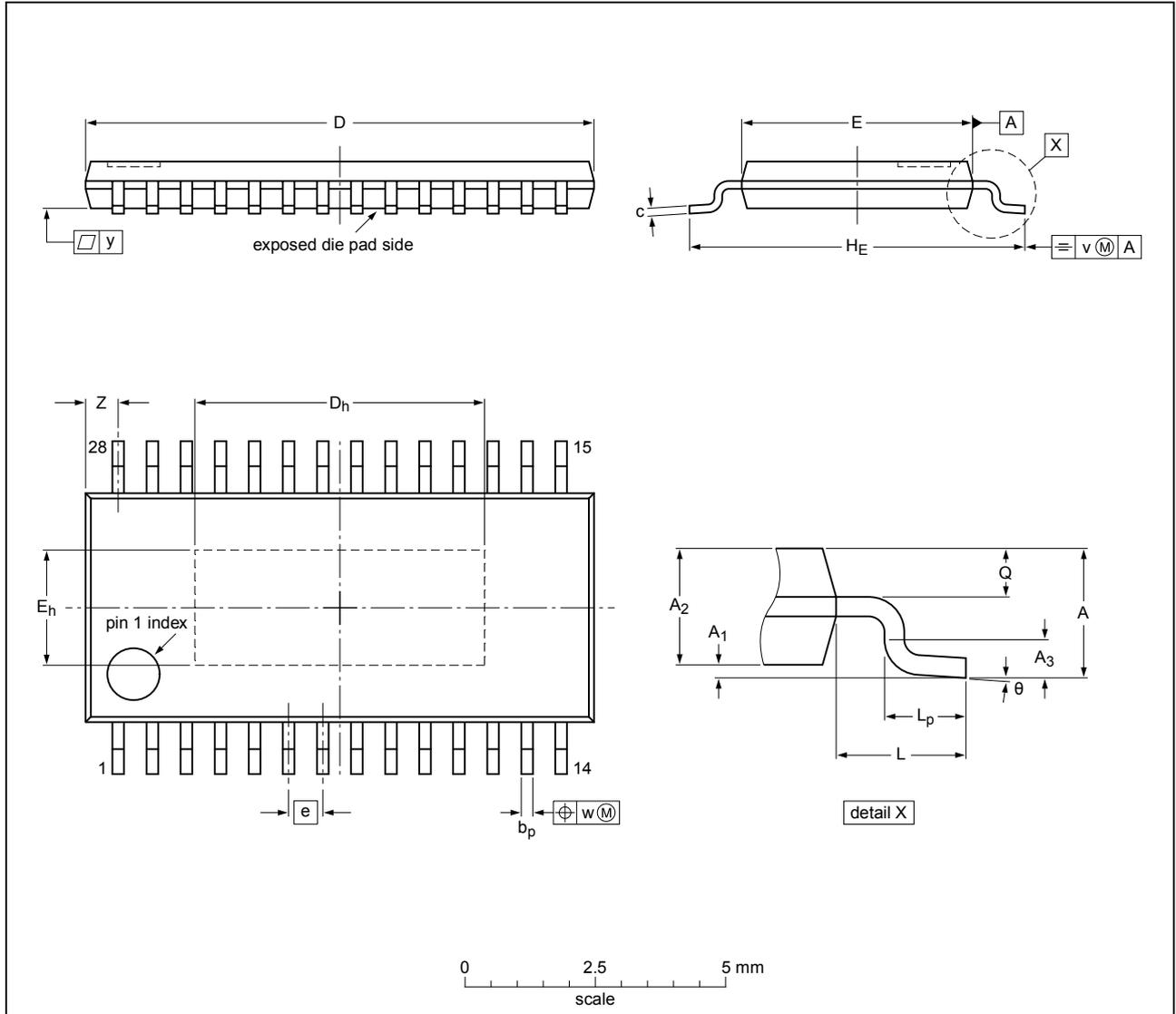
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.6	-	9.7	9.8	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	[tbd]	1.1	mm
A ₂	package height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	28	-	



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2. Package outline

HTSSOP28: plastic thermal enhanced thin shrink small outline package; 28 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed die pad SOT1172-2



Dimensions

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽²⁾	E _h	e	H _E	L	L _p	Q	v	w	y	Z	θ
max	1.1	0.15	0.95		0.30	0.20	9.8	5.6	4.5	2.3		6.6		0.75	0.40				0.80	8°
mm	nom	0.10	0.90	0.25	0.22	0.15	9.7	5.5	4.4	2.2	0.65	6.4	1.0	0.62	0.37	0.2	0.13	0.1	0.63	4°
	min		0.05	0.85		0.19	9.6	5.4	4.3	2.1		6.2		0.50	0.3				0.50	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1172-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1172-2	---	MO-153	---		10-07-06 10-07-13

Fig. 1. Package outline HTSSOP28 (SOT1172-2)

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3. Soldering

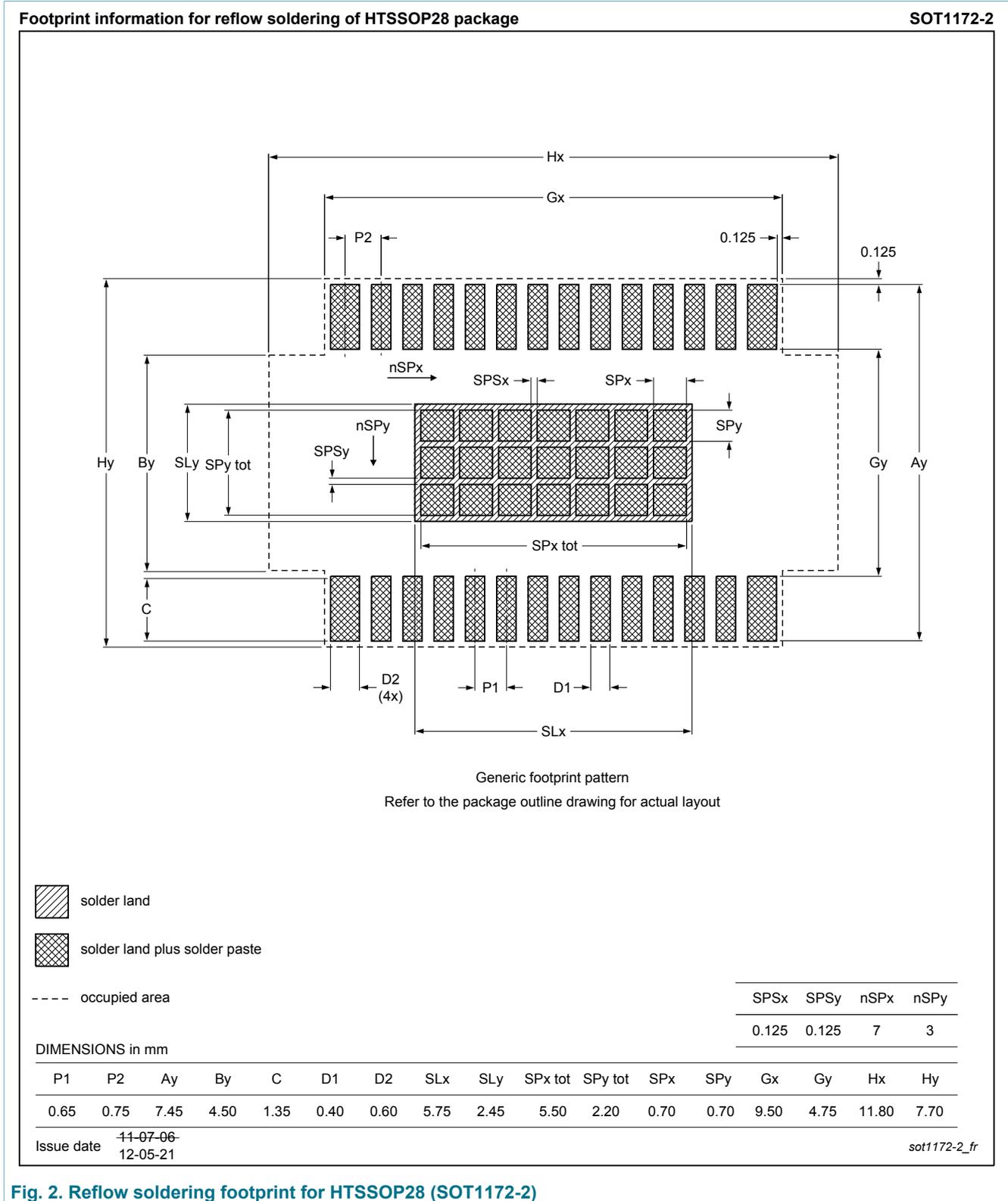


Fig. 2. Reflow soldering footprint for HTSSOP28 (SOT1172-2)

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4. Legal information

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